

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	("6391742").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/15 13:07
L2	5	("5798557" "5901031" "6036872" "6146917" "6232150").PN.	USPAT	OR	ON	2005/09/15 13:07
L3	5	("5798557" "5901031" "6036872" "6146917" "6232150").PN.	USPAT	OR	ON	2005/09/15 13:07
L4	11	"6391742".URPN.	USPAT	OR	ON	2005/09/15 13:07
L5	5	("5798557" "5901031" "6036872" "6146917" "6232150").PN.	USPAT	OR	ON	2005/09/15 13:07
L6	3208444	(via near hole) or (through near hole) or opening	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:07
L7	1032260	bump or solder\$6 or ball	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:07
L8	581073	pad	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:07
L9	114819	"glass substrate"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:07
L10	4399	((via near hole) or (through near hole) or opening) near8 (bump or solder\$6 or ball) near8 pad	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:07
L11	28359	"flip chip"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:07

L12	13	(((via near hole) or (through near hole) or opening) near8 (bump or solder\$6 or ball) near8 pad) same "glass substrate"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:07
L13	146	(((via near hole) or (through near hole) or opening) near8 (bump or solder\$6 or ball) near8 pad) and "glass substrate"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:07
L14	55	(((via near hole) or (through near hole) or opening) near8 (bump or solder\$6 or ball) near8 pad) and "glass substrate") and "flip chip"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:07
L15	23739343	(@ad<"20030224") or (@rlad<"20030224")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:07
L16	46	(((via near hole) or (through near hole) or opening) near8 (bump or solder\$6 or ball) near8 pad) and "glass substrate") and "flip chip") and ((@ad<"20030224") or (@rlad<"20030224"))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:07
L17	19	("5407864" "5422516" "5468681" "5495667" "5569963" "5604160" "5734201" "5790384" "5798557" "5821624" "5847456" "5851845" "5886409" "5972734" "6004867" "6037665" "6081026" "6081429" "6097098").PN.	USPAT	OR	ON	2005/09/15 13:07
L18	3170	(438/106).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/15 13:07
L19	1021	(438/125).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/15 13:07
L20	1047	(438/455).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/15 13:07

L21	237	(438/456).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/15 13:07
L22	2	("6300676").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/15 13:07
L23	3170	(438/106).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/15 13:07
L24	1218	L23 and (insulation or insulating or insulated)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:07
L25	912	L24 and (opening or via or hole)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:07
L26	928	L24 and (opening or via or hole or recess or recesses)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:07
L27	679	L26 and (solder or ball or bump)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:07
L28	71	L27 and ((glass transparent) near substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:07

L29	61	L28 and ((@ad<"20030224") or (@rlad<"20030224"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:07
L30	55	L29 and (bond or bonding or laminate or laminating)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:07
L31	145	(438/116).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/15 13:07
L32	2566	(438/612).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/15 13:07
L33	997	(438/723).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/15 13:07
L34	3704	L31 or L32 or L33	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:07
L35	1852	L34 and (insulation or insulating or insulated)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:07
L36	1439	L35 and (opening or via or hole)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:07

L37	490	L36 and (solder or ball or bump)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:07
L38	43	L37 and ((glass transparent) near substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:07
L39	35	L38 and ((@ad<"20030224") or (@rlad<"20030224"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:07
L40	145	(438/116).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/15 13:07
L41	2566	(438/612).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/15 13:07
L42	997	(438/723).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/15 13:07
L43	3704	L40 or L41 or L42	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:07
L44	1852	L43 and (insulation or insulating or insulated)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:07

L45	1439	L44 and (opening or via or hole)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:07
L46	490	L45 and (solder or ball or bump)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:07
L47	43	L46 and ((glass transparent) near substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:07
L48	35	L47 and ((@ad<"20030224") or (@rlad<"20030224"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:07
L49	221142	((glass or transparent) near2 substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:07
L50	10944	L49 near4 (hole or via or aperture or trench or gap or space or spacing)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:07
L51	1207	L50 same bond\$6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:07
L52	108	L51 same (solder or soldering or soldered or ball or paste)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:07

L53	60	"via hole" near4 "glass substrate"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:07
L54	60	"via hole" near4 "glass substrate"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:07
L55	4001	"glass substrate" near4 bond\$6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:07
L56	142	L55 near8 via	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:07
L57	371	"via hole" near4 glass	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:07
L58	33	L57 same (bump or solder or soldering)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:07
L59	1327	(438/613).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/15 13:07
L60	2	L57 and L59	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:07
L61	0	("2005/0009315").URPN.	USPAT	OR	ON	2005/09/15 13:07

L62	1761	melt\$6 near4 (ball or bump or solder or paste) near4 ("via hole" or hole or through-hole or gap or aperture or interconnect\$6 or plug)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:07
L63	6370	((glass or transparent) near (substrate or wafer)) near4 bond\$6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:07
L64	45	L62 and L63	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:07
L65	6370	((glass or transparent) near (substrate or wafer)) near4 bond\$6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:07
L66	1961	L65 same (solder or ball or bond)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:07
L67	106	L66 same melt\$6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:07
L68	78	L67 and ((@ad<"20030224") or (@riad<"20030224"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:07
L69	24056	"solder ball"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:07

L70	8466579	(via or hole or trench or recess or recess or opening or aperture)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:07
L71	250950	(glass or transparent) near2 (substrate or wafer or holder or board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:07
L72	4683	L69 near4 L70	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:07
L73	416	L72 and L71	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:07
L74	345	L73 and ((@ad<"20030224") or (@rlad<"20030224"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:07
L75	0	kapton near4 glass near4 stencil	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:07
L76	213	kapton near4 glass	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:07
L77	7440	((438/106) or (438/116) or (438/612) or (438/613) or (438/723)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/15 13:07

L78	173	L77 and L69 and L70 and L71	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:07
L79	144	L78 and ((@ad<"20030224") or (@rlad<"20030224"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:07
L80	112	L79 not L74	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:07
L81	2	("20040035917").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/15 13:07
L82	2	("6,300,676").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/15 13:07
L83	71	L27 and ((glass transparent) near substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:30